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Jameco Part Number 871498

# Single-Channel: 6N138, 6N139 Dual-Channel: HCPL-2730, HCPL-2731 Low Input Current High Gain Split Darlington Optocouplers

## Features

- Low current - 0.5 mA
- Superior CTR-2000%
- Superior CMR-10 kV/μs
- CTR guaranteed 0-70°C
- U.L. recognized (File # E90700)
- VDE recognized (File # 120915) Ordering option V, e.g., 6N138V
- Dual Channel - HCPL-2730
- HCPL-2731

## Applications

- Digital logic ground isolation
- Telephone ring detector
- EIA-RS-232C line receiver
- High common mode noise line receiver
- μP bus isolation
- Current loop receiver

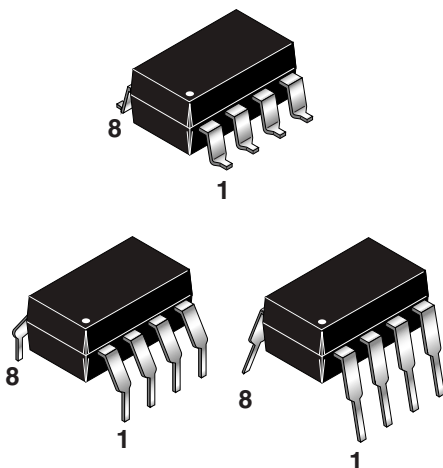
## Description

The 6N138/9 and HCPL-2730/HCPL-2731 optocouplers consist of an AlGaAs LED optically coupled to a high gain split darlington photodetector.

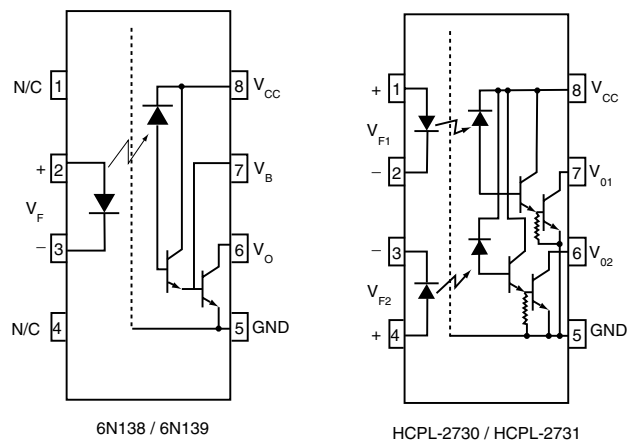
The split darlington configuration separating the input photodiode and the first stage gain from the output transistor permits lower output saturation voltage and higher speed operation than possible with conventional darlington phototransistor optocoupler. In the dual channel devices, HCPL-2730/HCPL2731, an integrated emitter - base resistor provides superior stability over temperature.

The combination of a very low input current of 0.5 mA and a high current transfer ratio of 2000% makes this family particularly useful for input interface to MOS, CMOS, LSTTL and EIA RS232C, while output compatibility is ensured to CMOS as well as high fan-out TTL requirements. An internal noise shield provides exceptional common mode rejection of 10 kV/μs.

## Package



## Schematic



**Absolute Maximum Ratings** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Value	Units
Storage Temperature	$T_{STG}$	-55 to +125	$^\circ\text{C}$
Operating Temperature	$T_{OPR}$	-40 to +85	$^\circ\text{C}$
Lead Solder Temperature (Wave solder only. See recommended reflow profile graph for SMD mounting)	$T_{SOL}$	260 for 10 sec	$^\circ\text{C}$
<b>EMITTER</b>			
DC/Average Forward Input Current	Each Channel	$I_F$ (avg)	20 mA
Peak Forward Input Current (50% duty cycle, 1 ms P.W.)	Each Channel	$I_F$ (pk)	40 mA
Peak Transient Input Current ( $\leq 1 \mu\text{s}$ P.W., 300 pps)		$I_F$ (trans)	1.0 A
Reverse Input Voltage	Each Channel	$V_R$	5 V
Input Power Dissipation	Each Channel	$P_D$	35 mW
<b>DETECTOR</b>			
Average Output Current	Each Channel	$I_O$ (avg)	60 mA
Emitter-Base Reverse Voltage	(6N138 and 6N139)	$V_{ER}$	0.5 V
Supply Voltage, Output Voltage	(6N138, HCPL-2730) (6N139, HCPL-2731)	$V_{CC}, V_O$	-0.5 to 7 V -0.5 to 18 V
Output Power Dissipation	Each Channel	$P_O$	100 mW

**Electrical Characteristics** ( $T_A = 0$  to  $70^\circ\text{C}$  Unless otherwise specified)**Individual Component Characteristics**

Parameter	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
<b>EMITTER</b>							
Input Forward Voltage	$T_A = 25^\circ\text{C}$ Each channel ( $I_F = 1.6 \text{ mA}$ )	$V_F$	All		1.30	1.7	V
						1.75	
Input Reverse Breakdown Voltage	( $T_A = 25^\circ\text{C}$ , $I_R = 10 \mu\text{A}$ ) Each Channel	$BV_R$	All	5.0	20		V
Temperature coefficient of forward voltage ( $I_F = 1.6 \text{ mA}$ )		$(\Delta V_F / \Delta T_A)$	All		-1.8		mV/ $^\circ\text{C}$
<b>DETECTOR</b>							
Logic high output current	( $I_F = 0 \text{ mA}$ , $V_O = V_{CC} = 18 \text{ V}$ ) Each Channel	$I_{OH}$	6N139		0.01	100	$\mu\text{A}$
			HCPL-2731				
	( $I_F = 0 \text{ mA}$ , $V_O = V_{CC} = 7 \text{ V}$ ) Each Channel		6N138		0.01	250	
			HCPL-2730				
Logic low supply	( $I_F = 1.6 \text{ mA}$ , $V_O = \text{Open}$ ) ( $V_{CC} = 18 \text{ V}$ )	$I_{CCL}$	6N138		0.4	1.5	mA
	( $I_{F1} = I_{F2} = 1.6 \text{ mA}$ , $V_{CC} = 18 \text{ V}$ ) ( $V_{O1} - V_{O2} = \text{Open}$ , $V_{CC} = 7 \text{ V}$ )		6N139				
			HCPL-2731 HCPL-2730		1.3	3	
Logic high supply	( $I_F = 0 \text{ mA}$ , $V_O = \text{Open}$ , $V_{CC} = 18 \text{ V}$ )	$I_{CCH}$	6N135 6N136		0.05	10	$\mu\text{A}$
	( $I_{F1} = I_{F2} = 0 \text{ mA}$ , $V_{CC} = 18 \text{ V}$ ) ( $V_{O1} - V_{O2} = \text{Open}$ , $V_{CC} = 7 \text{ V}$ )		HCPL-2731		0.10	20	
			HCPL-2730				

\*\* All Typicals at  $T_A = 25^\circ\text{C}$

**Transfer Characteristics** ( $T_A = 0$  to  $70^\circ\text{C}$  Unless otherwise specified)

Parameter	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
COUPLED Current transfer ratio (Note 1, 2)	( $I_F = 0.5 \text{ mA}$ , $V_O = 0.4 \text{ V}$ , $V_{CC} = 4.5 \text{ V}$ )	CTR	6N139	400	1100		%
	Each Channel		HCPL-2731		3500		
	( $I_F = 1.6 \text{ mA}$ , $V_O = 0.4 \text{ V}$ , $V_{CC} = 4.5 \text{ V}$ )	Each Channel	6N139	500	1300		%
	Each Channel		HCPL-2731		2500		
	( $I_F = 1.6 \text{ mA}$ , $V_O = 0.4 \text{ V}$ , $V_{CC} = 4.5 \text{ V}$ )	Each Channel	6N138	300	1300		%
	Each Channel		HCPL-2730		2500		
Logic low output voltage output voltage (Note 2)	( $I_F = 0.5 \text{ mA}$ , $I_O = 2 \text{ mA}$ , $V_{CC} = 4.5 \text{ V}$ )	$V_{OL}$	6N139		0.08	0.4	V
	( $I_F = 1.6 \text{ mA}$ , $I_O = 8 \text{ mA}$ , $V_{CC} = 4.5 \text{ V}$ )		6N139		0.01		
	Each Channel	HCPL-2731					
	( $I_F = 0.5 \text{ mA}$ , $I_O = 15 \text{ mA}$ , $V_{CC} = 4.5 \text{ V}$ )	Each Channel	6N139		0.13	0.4	
	Each Channel		HCPL-2731				
	( $I_F = 12 \text{ mA}$ , $I_O = 24 \text{ mA}$ , $V_{CC} = 4.5 \text{ V}$ )	Each Channel	6N139		0.20	0.4	
	Each Channel		HCPL-2731				
	( $I_F = 1.6 \text{ mA}$ , $I_O = 4.8 \text{ mA}$ , $V_{CC} = 4.5 \text{ V}$ )	Each Channel	6N138		0.10	0.4	
Each Channel	HCPL-2730						

\*\* All Typicals at  $T_A = 25^\circ\text{C}$

**Switching Characteristics** ( $T_A = 0$  to  $70^\circ\text{C}$  unless otherwise specified.,  $V_{CC} = 5\text{ V}$ )

Parameter	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
Propagation delay time to logic low (Note 2) (Fig. 22)	$(R_L = 4.7\text{ k}\Omega, I_F = 0.5\text{ mA})$ Each Channel $T_A = 25^\circ\text{C}$	$T_{PHL}$	6N139			30	$\mu\text{s}$
			HCPL-2731		4	25	
	$(R_L = 4.7\text{ k}\Omega, I_F = 0.5\text{ mA})$ Each Channel $T_A = 25^\circ\text{C}$	$T_{PHL}$	6N139			2	$\mu\text{s}$
			HCPL-2730		3	100	
	$(R_L = 270\ \Omega, I_F = 12\text{ mA})$ Each Channel $T_A = 25^\circ\text{C}$	$T_{PHL}$	6N139			0.2	$\mu\text{s}$
			HCPL-2730		0.3	3	
	$(R_L = 270\ \Omega, I_F = 12\text{ mA})$ Each Channel $T_A = 25^\circ\text{C}$	$T_{PHL}$	6N138			15	$\mu\text{s}$
			HCPL-2731		1.5	10	
$(R_L = 2.2\text{ k}\Omega, I_F = 1.6\text{ mA})$ Each Channel $T_A = 25^\circ\text{C}$	$T_{PHL}$	6N138			25	$\mu\text{s}$	
		HCPL-2730		1	20		
Propagation delay time to logic high (Note 2) (Fig. 22)	$(R_L = 4.7\text{ k}\Omega, I_F = 0.5\text{ mA})$ Each Channel $T_A = 25^\circ\text{C}$	$T_{PLH}$	6N139			90	$\mu\text{s}$
			HCPL-2731		12	60	
	$(R_L = 4.7\text{ k}\Omega, I_F = 0.5\text{ mA})$ Each Channel $T_A = 25^\circ\text{C}$	$T_{PLH}$	6N139			10	$\mu\text{s}$
			HCPL-2731		22	7	
	$(R_L = 270\ \Omega, I_F = 12\text{ mA})$ Each Channel $T_A = 25^\circ\text{C}$	$T_{PLH}$	6N139			1.3	$\mu\text{s}$
			HCPL-2730		5	15	
	$(R_L = 270\ \Omega, I_F = 12\text{ mA})$ Each Channel $T_A = 25^\circ\text{C}$	$T_{PLH}$	6N138			50	$\mu\text{s}$
			HCPL-2731		7	35	
$(R_L = 2.2\text{ k}\Omega, I_F = 1.6\text{ mA})$ Each Channel $T_A = 25^\circ\text{C}$	$T_{PLH}$	6N138			16	$\mu\text{s}$	
		HCPL-2730/1		16			
Common mode transient immunity at logic high	$(I_F = 0\text{ mA},  V_{CM}  = 10\text{ V}_{P-P})$ $T_A = 25^\circ\text{C}, (R_L = 2.2\text{ k}\Omega)$ (Note 3) (Fig. 23) Each Channel	$ICM_{HI}$	6N138	1,000	10,000		$\text{V}/\mu\text{s}$
			6N139				
Common mode transient immunity at logic low	$(I_F = 1.6\text{ mA},  V_{CM}  = 10\text{ V}_{P-P})$ $T_A = 25^\circ\text{C}, (R_L = 2.2\text{ k}\Omega)$ (Note 3) (Fig. 23) Each Channel	$ICM_{LI}$	6N138	1,000	10,000		$\text{V}/\mu\text{s}$
			6N139				
			HCPL-2730				
			HCPL-2731				

\*\* All Typical at  $T_A = 25^\circ\text{C}$

**Isolation Characteristics** ( $T_A = 0$  to  $70^\circ\text{C}$  Unless otherwise specified)

Characteristics	Test Conditions	Symbol	Min	Typ**	Max	Unit
Input-output insulation leakage current	(Relative humidity = 45%) ( $T_A = 25^\circ\text{C}$ , $t = 5$ s) ( $V_{I-O} = 3000$ VDC) (Note 8)	$I_{I-O}$			1.0	$\mu\text{A}$
Withstand insulation test voltage	( $RH \leq 50\%$ , $T_A = 25^\circ\text{C}$ , $I_{I-O} \leq 2$ $\mu\text{A}$ ) (Note 4) ( $t = 1$ min.)	$V_{ISO}$	2500			$V_{RMS}$
Resistance (input to output)	(Note 4) ( $V_{I-O} = 500$ VDC)	$R_{I-O}$		$10^{12}$		$\Omega$
Capacitance (input to output)	(Note 4, 5) ( $f = 1$ MHz)	$C_{I-O}$		0.6		pF
Input-Input Insulation leakage current	( $RH \leq 45\%$ , $V_{I-I} = 500$ VDC) (Note 6) $t = 5$ s, (HCPL-2730/2731 only)	$I_{I-I}$		0.005		$\mu\text{A}$
Input-Input Resistance	( $V_{I-I} = 500$ VDC) (Note 6) (HCPL-2730/2731 only)	$R_{I-I}$		$10^{11}$		$\Omega$
Input-Input Capacitance	( $f = 1$ MHz) (Note 6) (HCPL-2730/2731 only)	$C_{I-I}$		0.03		pF

\*\* All Typical values at  $T_A = 25^\circ\text{C}$

**Notes**

- Current Transfer Ratio is defined as a ratio of output collector current,  $I_O$ , to the forward LED input current,  $I_F$  times 100%.
- Pin 7 open. (6N138 and 6N139 only)
- Common mode transient immunity in logic high level is the maximum tolerable (positive)  $dV_{CM}/dt$  on the leading edge of the common mode pulse signal  $V_{CM}$ , to assure that the output will remain in a logic high state (i.e.,  $V_O > 2.0$  V). Common mode transient immunity in logic low level is the maximum tolerable (negative)  $dV_{CM}/dt$  on the trailing edge of the common mode pulse signal,  $V_{CM}$ , to assure that the output will remain in a logic low state (i.e.,  $V_O < 0.8$  V).
- Device is considered a two terminal device: Pins 1, 2, 3 and 4 are shorted together and Pins 5, 6, 7 and 8 are shorted together.
- For dual channel devices,  $C_{I-O}$  is measured by shorting pins 1 and 2 or pins 3 and 4 together and pins 5 through 8 shorted together.
- Measured between pins 1 and 2 shorted together, and pins 3 and 4 shorted together.

## Electrical Characteristics (T<sub>A</sub> = 25°C unless otherwise specified)

Current Limiting Resistor Calculations

$$R_1 \text{ (Non-Invert)} = \frac{V_{DD1} - V_{DF} - V_{OL1}}{I_F}$$

$$R_1 \text{ (Invert)} = \frac{V_{DD1} - V_{OH1} - V_{DF}}{I_F}$$

$$R_2 = \frac{V_{DD2} - V_{OLX} (@ I_L - I_2)}{I_L}$$

Where:

V<sub>DD1</sub> - Input Supply Voltage

V<sub>DD2</sub> - Output Supply Voltage

V<sub>DF</sub> - Diode Forward Voltage

V<sub>OL1</sub> - Logic "0" Voltage of Driver

V<sub>OH1</sub> - Logic "1" Voltage of Driver

I<sub>F</sub> - Diode Forward Current

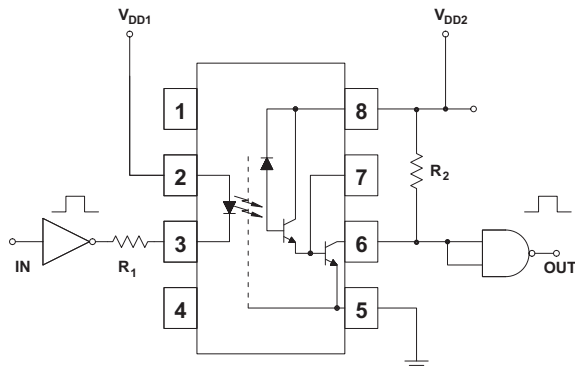
V<sub>OLX</sub> - Saturation Voltage of Output Transistor

I<sub>L</sub> - Load Current Through Resistor R<sub>2</sub>

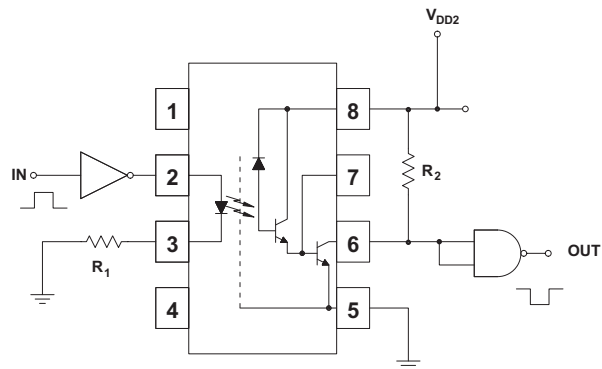
I<sub>2</sub> - Input Current of Output Gate

INPUT		R1 (V)	OUTPUT						
			CMOS @ 5 V	CMOS @ 10 V	74XX	74LXX	74SXX	74LSXX	74HXX
			R2 (V)	R2 (V)	R2 (V)	R2 (V)	R2 (V)	R2 (V)	R2 (V)
CMOS @ 5 V	NON-INV.	2000	1000	2200	750	1000	1000	1000	560
	INV.	510							
CMOS @ 10 V	NON-INV.	5100							
	INV.	4700							
74XX	NON-INV.	2200							
	INV.	180							
74LXX	NON-INV.	1800							
	INV.	100							
74SXX	NON-INV.	2000							
	INV.	360							
74LSXX	NON-INV.	2000							
	INV.	180							
74HXX	NON-INV.	2000							
	INV.	180							

**Fig. 1 Resistor Values for Logic Interface**

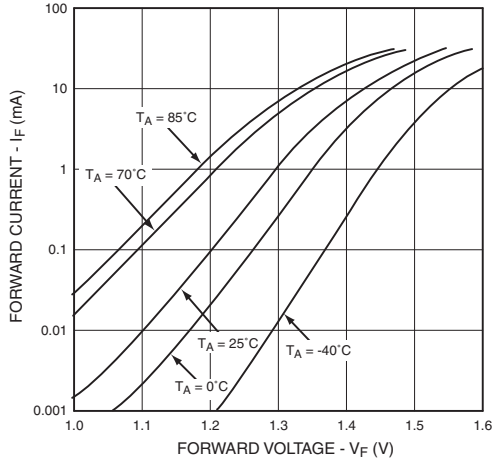


**Fig. 2 Non-Inverting Logic Interface**

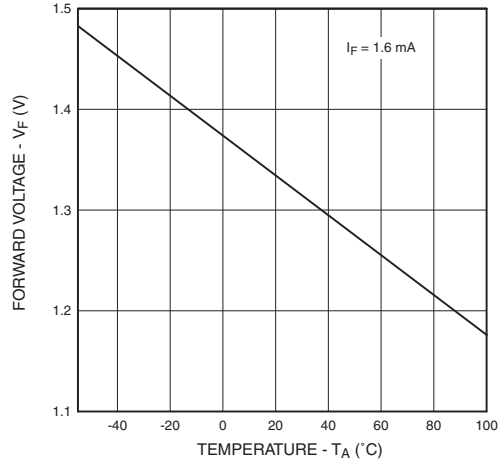


**Fig. 3 Inverting Logic Interface**

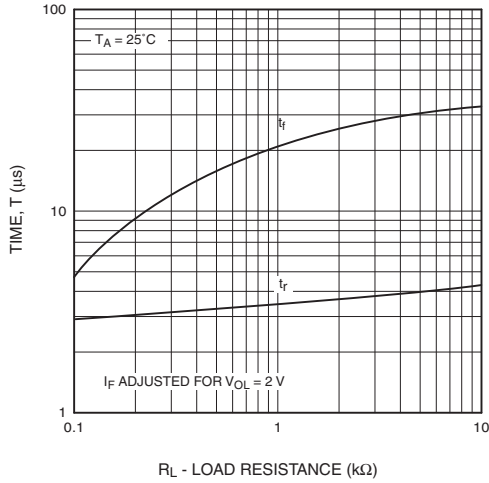
**Fig. 4 LED Forward Current vs. Forward Voltage**



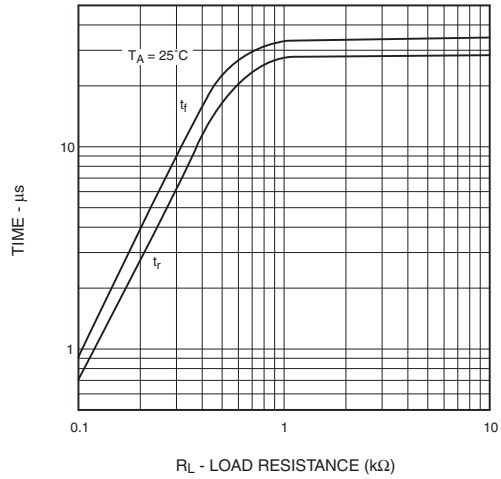
**Fig. 5 LED Forward Voltage vs. Temperature**



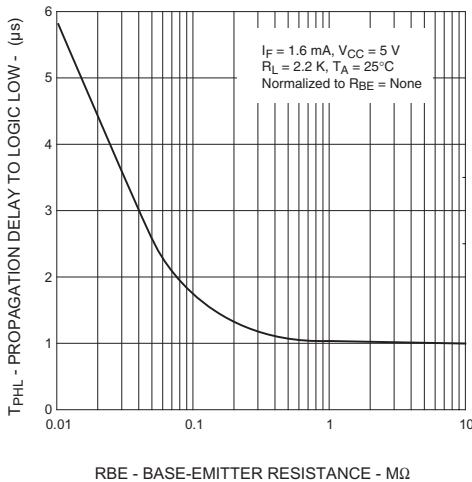
**Fig. 6 Non-saturated Rise and Fall Times vs. Load Resistance (6N138 / 6N139 Only)**



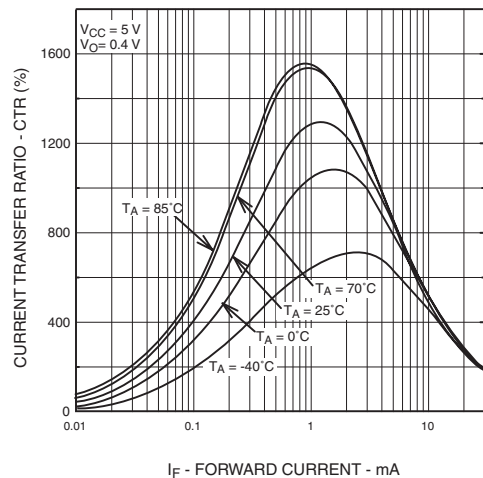
**Fig. 7 Non-saturated Rise and Fall Times vs. Load Resistance (HCPL-2730 / HCPL-2731 Only)**



**Fig. 8 Propagation Delay To Logic Low vs. Base-Emitter Resistance (HCPL-2730 / HCPL-2731 Only)**

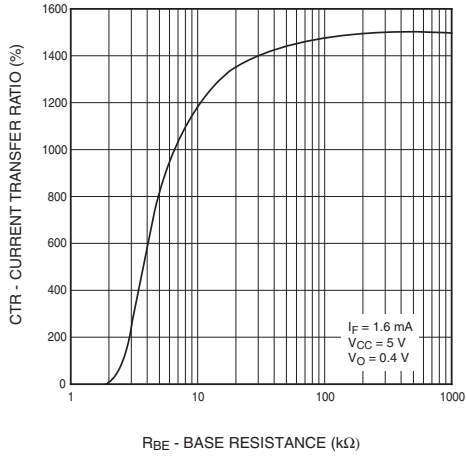


**Fig. 9 Current Transfer Ratio vs. Forward Current (6N138 / 6N139 Only)**

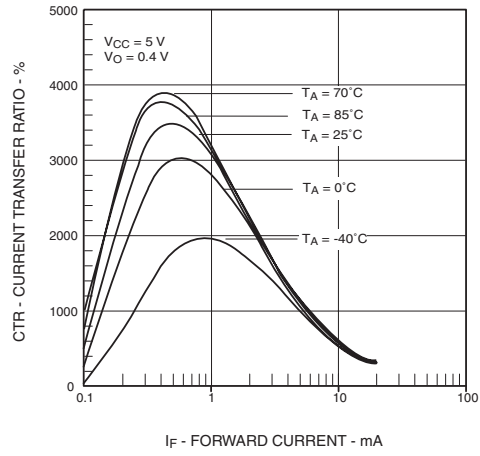




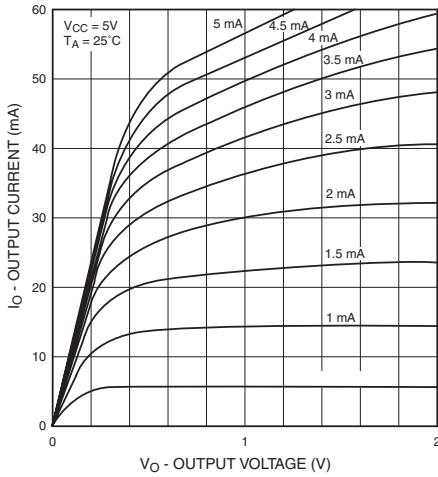
**Fig. 10 Current Transfer Ratio vs. Base-Emitter Resistance (6N138 / 6N139 Only)**



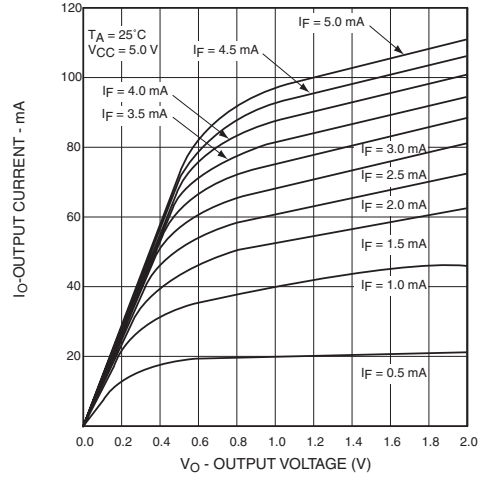
**Fig. 11 Current Transfer Ratio vs. Forward Current (HCPL-2730 / HCPL-2731 Only)**



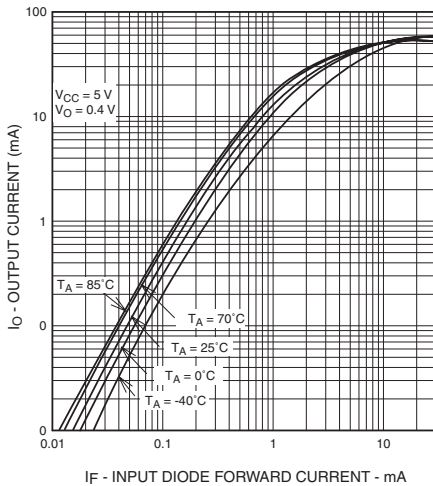
**Fig. 12 Output Current vs Output Voltage (6N138 / 6N139 Only)**



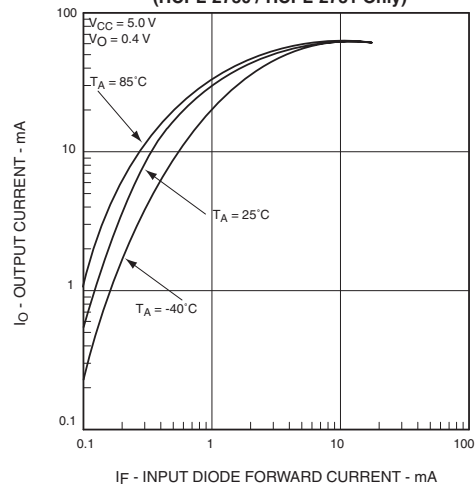
**Fig. 13 Output Current vs Output Voltage (HCPL-2730 / HCPL-2731 Only)**



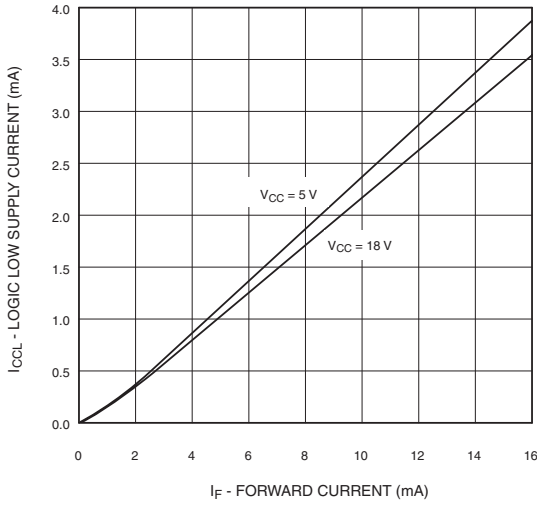
**Fig. 14 Output Current vs. Input Diode Forward Current (6N138 / 6N139 Only)**



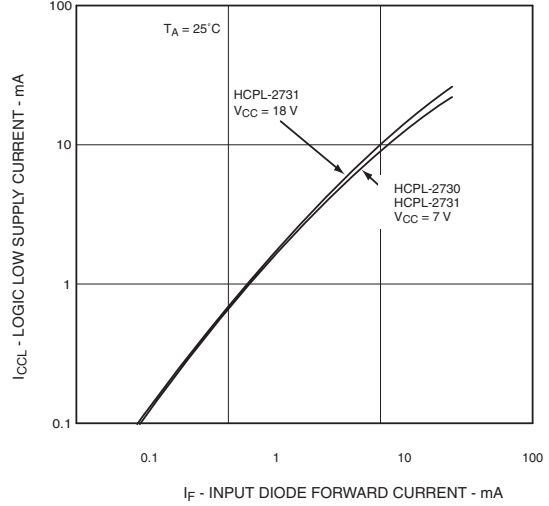
**Fig. 15 Output Current vs Input Diode Forward Current (HCPL-2730 / HCPL-2731 Only)**



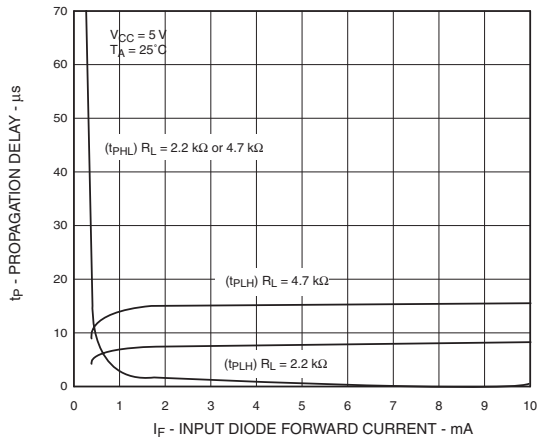
**Fig. 16 Logic Low Supply Current vs. Input Diode Forward Current (6N138 / 6N139 Only)**



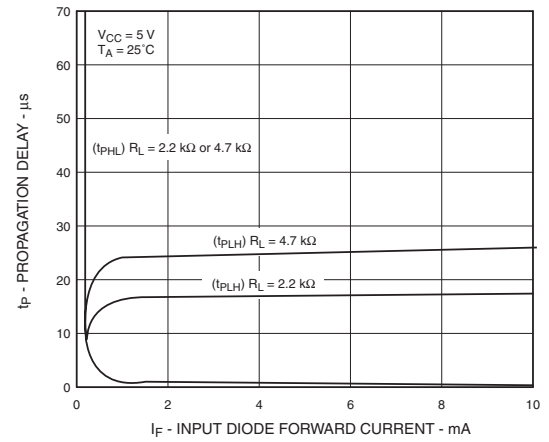
**Fig. 17 Logic Low Supply Current vs. Input Diode Forward Current (HCPL-2730 / HCPL-2731 Only)**



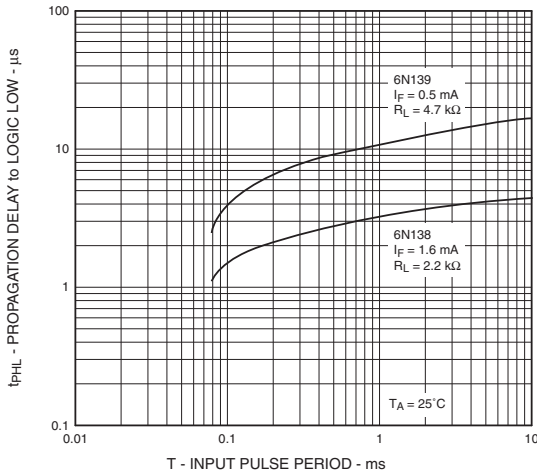
**Fig. 18 Propagation Delay vs. Input Diode Forward Current (6N138 / 6N139 Only)**



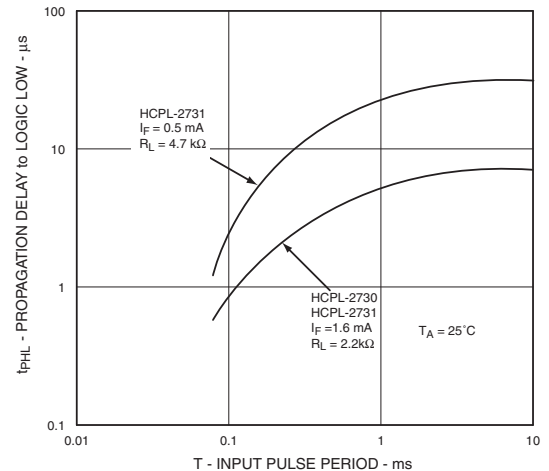
**Fig. 19 Propagation Delay vs. Input Diode Forward Current (HCPL-2730 / HCPL-2731 Only)**



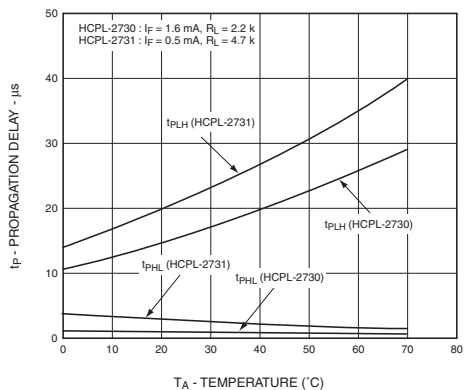
**Fig. 20 Propagation Delay to Logic Low vs. Pulse Period (6N138 / 6N139 Only)**



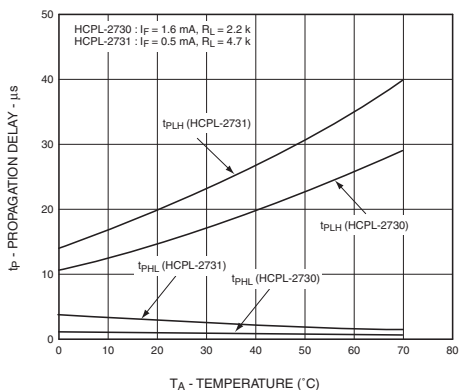
**Fig. 21 Propagation Delay to Logic Low vs. Pulse Period (HCPL-2730 / HCPL-2731 Only)**

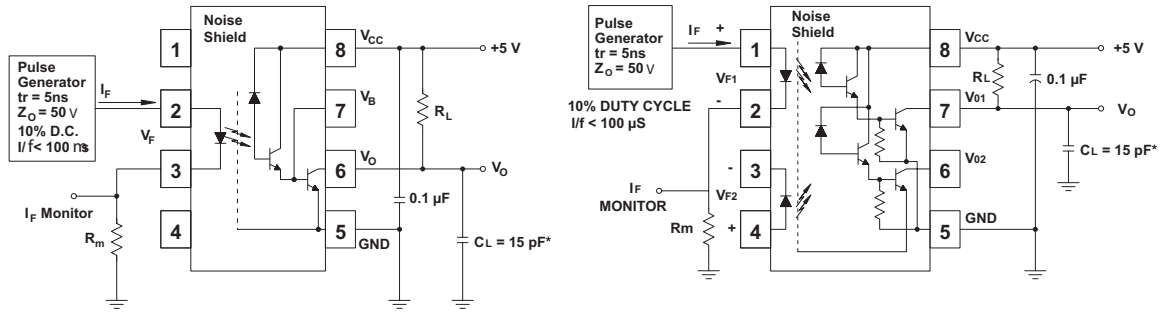


**Fig. 22 Propagation Delay vs. Temperature (6N138 / 6N139 Only)**



**Fig. 23 Propagation Delay vs. Temperature (HCPL-2730 / HCPL-2731 Only)**





Test Circuit for 6N138, 6N139

Test Circuit for HCPL-2730 and HCPL-2731

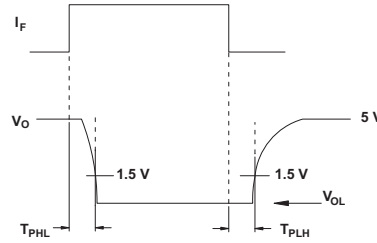
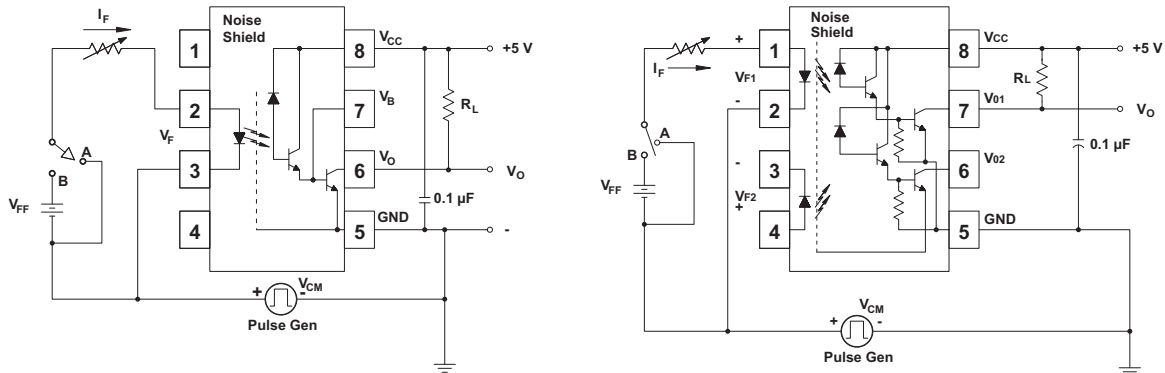


Fig. 22 Switching Time Test Circuit



Test Circuit for 6N138 and 6N139

Test Circuit for HCPL-2730 and HCPL-2731

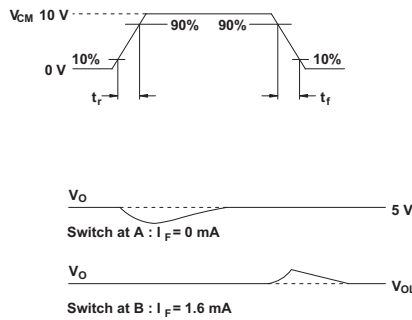
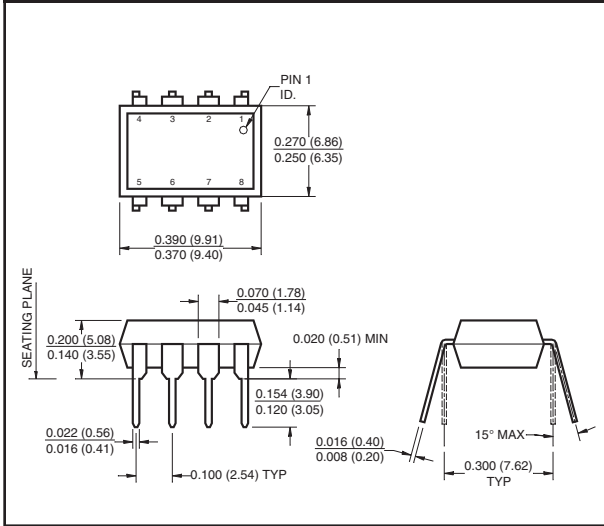
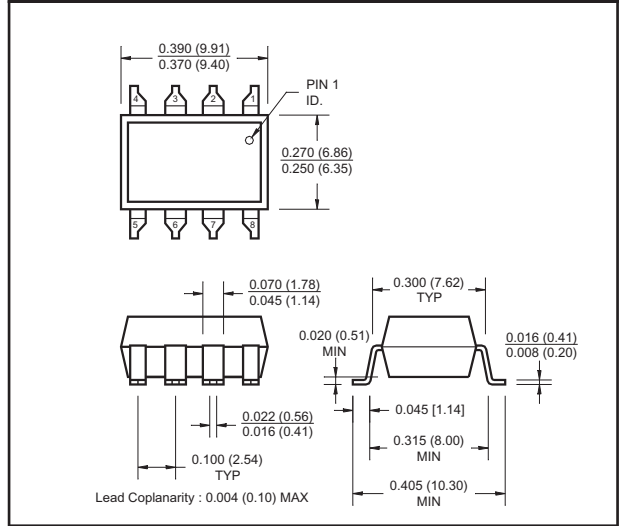


Fig. 23 Common Mode Immunity Test Circuit

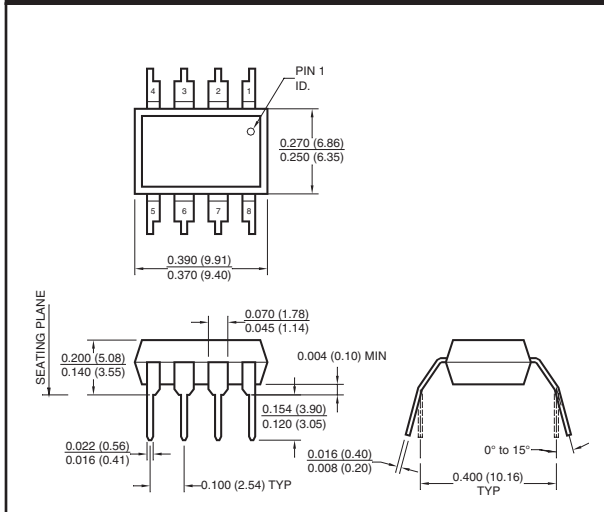
### Package Dimensions (Through Hole)



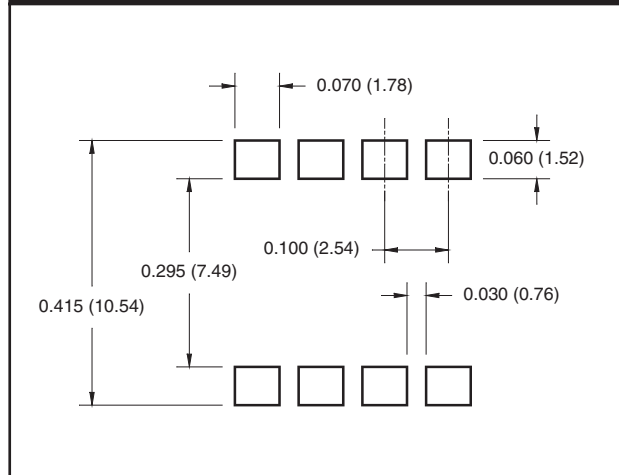
### Package Dimensions (Surface Mount)



### Package Dimensions (0.4" Lead Spacing)



### Recommended Pad Layout for Surface Mount Leadform



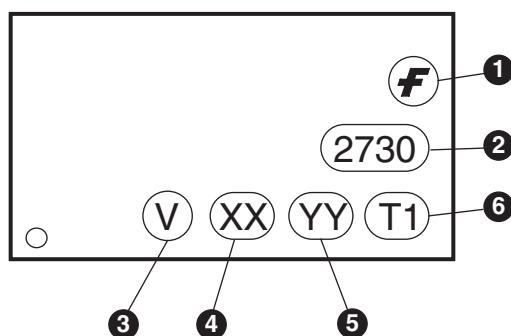
**NOTE**

All dimensions are in inches (millimeters)

### Ordering Information

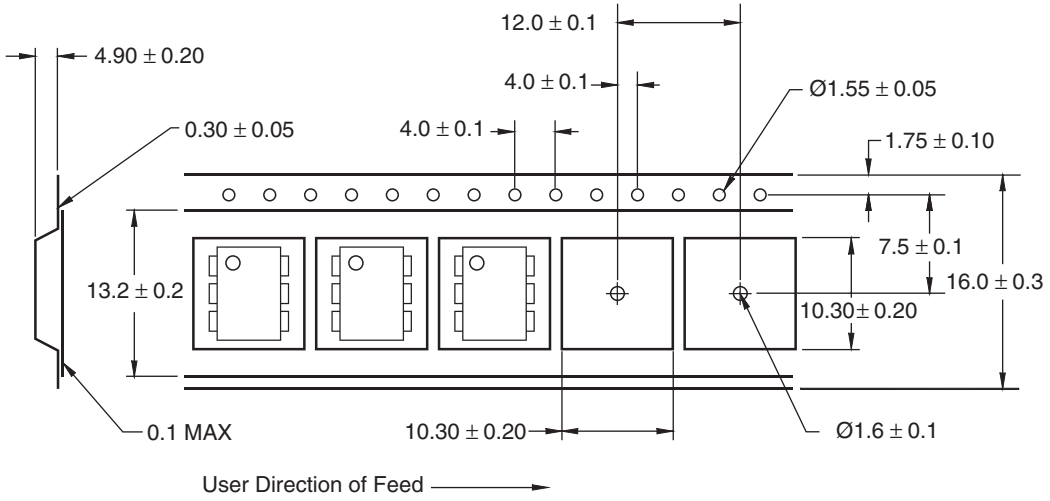
Option	Example Part Number	Description
S	6N138S	Surface Mount Lead Bend
SD	6N138SD	Surface Mount; Tape and reel
W	6N138W	0.4" Lead Spacing
V	6N138V	VDE0884
WV	6N138WV	VDE0884; 0.4" lead spacing
SV	6N138SV	VDE0884; surface mount
SDV	6N138SDV	VDE0884; surface mount; tape and reel

### Marking Information

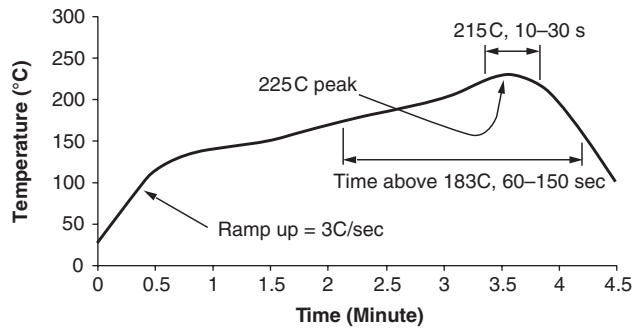


Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	Two digit year code, e.g., '03'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

### Tape Specifications



### Reflow Profile



- Peak reflow temperature: 225C (package surface temperature)
- Time of temperature higher than 183C for 60-150 seconds
- One time soldering reflow is recommended

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CoolFET <sup>™</sup>	I <sup>2</sup> C <sup>™</sup>	PACMAN <sup>™</sup>	SuperFET <sup>™</sup>	
CROSSVOLT <sup>™</sup>	i-Lo <sup>™</sup>	POP <sup>™</sup>	SuperSOT <sup>™</sup> -3	
DOME <sup>™</sup>	ImpliedDisconnect <sup>™</sup>	Power247 <sup>™</sup>	SuperSOT <sup>™</sup> -6	
EcoSPARK <sup>™</sup>	IntelliMAX <sup>™</sup>	PowerEdge <sup>™</sup>	SuperSOT <sup>™</sup> -8	
E <sup>2</sup> CMOS <sup>™</sup>	ISOPLANAR <sup>™</sup>	PowerSaver <sup>™</sup>	SyncFET <sup>™</sup>	
EnSigna <sup>™</sup>	LittleFET <sup>™</sup>	PowerTrench <sup>®</sup>	TCM <sup>™</sup>	
FACT <sup>™</sup>	MICROCOUPLER <sup>™</sup>	QFET <sup>®</sup>	TinyBoost <sup>™</sup>	
FAST <sup>®</sup>	MicroFET <sup>™</sup>	QS <sup>™</sup>	TinyBuck <sup>™</sup>	
FASTr <sup>™</sup>	MicroPak <sup>™</sup>	QT Optoelectronics <sup>™</sup>	TinyPWM <sup>™</sup>	
FPS <sup>™</sup>	MICROWIRE <sup>™</sup>	Quiet Series <sup>™</sup>	TinyPower <sup>™</sup>	
FRFET <sup>™</sup>	MSX <sup>™</sup>	RapidConfigure <sup>™</sup>	TinyLogic <sup>®</sup>	
	MSXPro <sup>™</sup>	RapidConnect <sup>™</sup>	TINYOPTO <sup>™</sup>	
Across the board. Around the world. <sup>™</sup>		μSerDes <sup>™</sup>	TruTranslation <sup>™</sup>	
The Power Franchise <sup>®</sup>		ScalarPump <sup>™</sup>	UHC <sup>™</sup>	
Programmable Active Droop <sup>™</sup>				

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## PRODUCT STATUS DEFINITIONS

### Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

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